

1 ABSTRACT OF THE DISCLOSURE

2 In one aspect, the invention includes a method of forming
3 integrated circuit packages. A base having a plurality of pins extending
4 upwardly therefrom is provided. A support is provided over the base.
5 The support has an upper surface and a plurality of holes extending
6 therethrough. The pins extend through the holes and upwardly beyond
7 the upper surface of the support. An actuator is provided beneath the
8 support. A board having a plurality of integrated circuits bonded thereto
9 is provided. The integrated circuits form a repeating pattern of
10 integrated circuit packages across the board, and the board has a
11 plurality of holes extending through it. The board is placed over the
12 support upper surface with the pins extending into the holes in the
13 board. While the board is over the support upper surface, it is cut to
14 separate the integrated circuit packages from one another. After the
15 cutting, the support is vertically displaced by the actuator to lift the
16 support off the pins.

17 In another aspect, the invention encompasses an integrated circuit
18 package separator for separating integrated circuit packages from a board.

19

20

21

22

23